

FEATURES

- Dual Device Module
- Electrically Isolated Package
- Pressure Contact Construction
- International Standard Footprint
- Alumina (Non Toxic) Isolation Medium
- Integral Water Cooled Heatsink

APPLICATIONS

- Welding

VOLTAGE RATINGS

Type Number	Repetitive Peak Voltages	Conditions
	V_{DRM} V_{RRM}	
MP04TT1400-28	2800	$T_{vj} = 0^\circ \text{ to } 125^\circ\text{C}$, $I_{DRM} = I_{RRM} = 50\text{mA}$ $V_{DSM} = V_{RSM} =$ $V_{DRM} = V_{RRM} + 100\text{V}$ respectively
MP04TT1400-27	2700	
MP04TT1400-26	2600	
MP04TT1400-25	2500	

Lower voltage grades available

ORDERING INFORMATION

Order As:

Order As:

- MP04TT1400-XX-W2** 1/4 - 18 NPT connection
MP04TT1400-XX-W3 1/4 - 18 NPT connection
MP04TT1400-XX-W3A 1/4 - 18 NPT water connection thread

XX shown in the part number about represents $V_{DRM}/100$ selection required, eg. MP04TT1400-27-W2

Note: When ordering, please use the complete part number.

KEY PARAMETERS

V_{DRM}	2800V
$I_{LINE(cont.)}$	1185A
$I_{LINE(20cy./50\%)}$	1508A
$I_{TSM(per\ arm)}$	11250A
V_{isol}	3000V

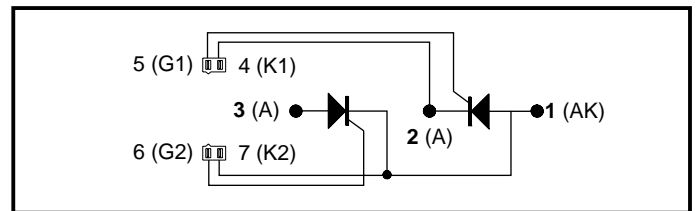


Fig. 1 TT Circuit diagram

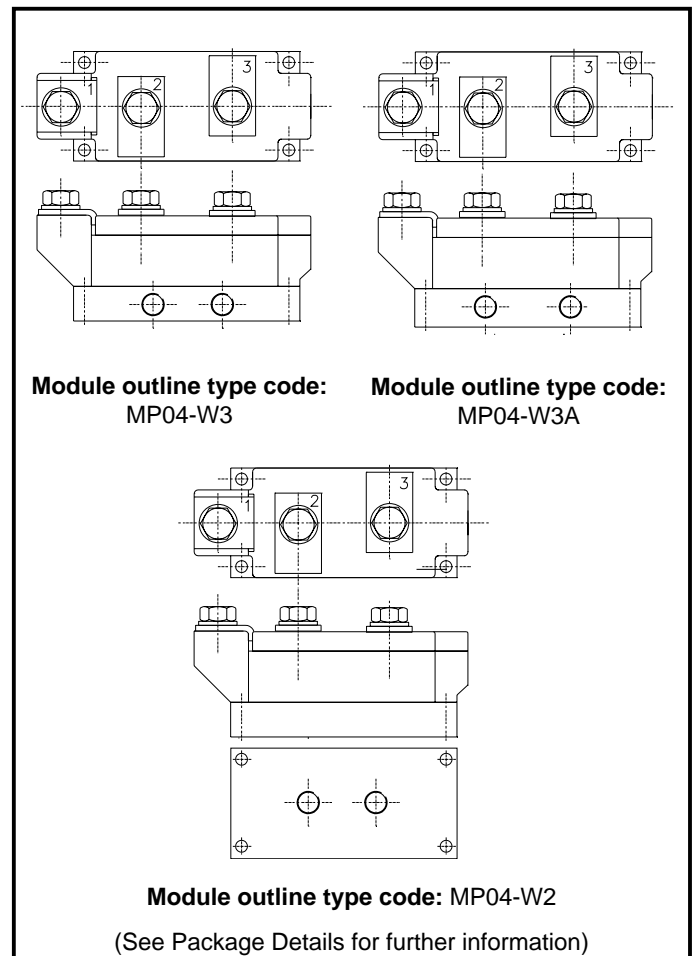


Fig. 2 Module package variants - (not to scale)

ABSOLUTE MAXIMUM CURRENT RATINGS

Stresses above those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed. Exposure to Absolute Maximum Ratings may affect device reliability.

Symbol	Parameter	Test Conditions	Max.	Units	
I_{LINE}	Max. controllable RMS line current - single phase	Continuous 50/60Hz 4.5 Ltr/min	$T_{water (in)} = 25^{\circ}C$	1185	A
			$T_{water (in)} = 40^{\circ}C$	1060	A
		20 cycles, 50% duty cycle 4.5 Ltr/min	$T_{water (in)} = 25^{\circ}C$	1668	A
			$T_{water (in)} = 40^{\circ}C$	1508	A
I_{TSM}	Surge (non-repetitive) on-current	10ms half sine, $T_j = 125^{\circ}C$	11.25	kA	
I^2t	I^2t for fusing	$V_R = 0$	0.633×10^6	A^2s	
I_{TSM}	Surge (non-repetitive) on-current	10ms half sine, $T_j = 125^{\circ}C$	9	kA	
I^2t	I^2t for fusing	$V_R = 50\% V_{DRM}$	0.506×10^6	A^2s	
V_{isol}	Isolation voltage	Commoned terminals to base plate. AC RMS, 1 min, 50Hz	3000	V	

THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions	Min.	Max.	Units
$R_{th(j-w)}$	Thermal resistance - junction to water (per thyristor)	dc, 4.5 Ltr/min	-	0.102	$^{\circ}C/kW$
		Half wave, 4.5 Ltr/min	-	0.106	$^{\circ}C/kW$
		3 Phase, 4.5 Ltr/min	-	0.112	$^{\circ}C/kW$
T_{vj}	Virtual junction temperature	Reverse (blocking)	-	125	$^{\circ}C$
T_{stg}	Storage temperature range	-	-40	125	$^{\circ}C$
-	Screw torque	Mounting - M6	6(53)	-	Nm (lb.ins)
		Electrical connections - M10	-	12(106)	Nm (lb.ins)
-	Weight (nominal)	-	-	Refer to drawings	g

DYNAMIC CHARACTERISTICS

Symbol	Parameter	Test Conditions	Min.	Max.	Units
I_{RRM}/I_{DRM}	Peak reverse and off-state current	At V_{RRM}/V_{DRM} , $T_j = 125^\circ\text{C}$	-	50	mA
dV/dt	Linear rate of rise of off-state voltage	To 67% V_{DRM} , $T_j = 125^\circ\text{C}$	-	1000	V/ μs
dI/dt	Rate of rise of on-state current	From 67% V_{DRM} to 500A, gate source 10V, 5 Ω $t_r = 0.5\mu\text{s}$, $T_j = 125^\circ\text{C}$	-	500	A/ μs
$V_{T(TO)}$	Threshold voltage	At $T_{vj} = 125^\circ\text{C}$	-	0.91	V
r_T	On-state slope resistance	At $T_{vj} = 125^\circ\text{C}$	-	0.65	m Ω

Note: The data given in this datasheet with regard to forward voltage drop is for calculation of the power dissipation in the semiconductor elements only. Forward voltage drops measured at the power terminals of the module will be in excess of these figures due to the impedance of the busbar from the terminal to the semiconductor.

GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
V_{GT}	Gate trigger voltage	$V_{DRM} = 5\text{V}$, $T_{case} = 25^\circ\text{C}$	3.5	V
I_{GT}	Gate trigger current	$V_{DRM} = 5\text{V}$, $T_{case} = 25^\circ\text{C}$	200	mA
V_{GD}	Gate non-trigger voltage	At V_{DRM} , $T_{case} = 125^\circ\text{C}$	0.25	V
V_{FGM}	Peak forward gate voltage	Anode positive with respect to cathode	30	V
V_{FGN}	Peak forward gate voltage	Anode negative with respect to cathode	0.25	V
V_{RGM}	Peak reverse gate voltage	-	5	V
I_{FGM}	Peak forward gate current	Anode positive with respect to cathode	10	A
P_{GM}	Peak gate power	See table fig. 5	150	W
$P_{G(AV)}$	Mean gate power	-	10	W

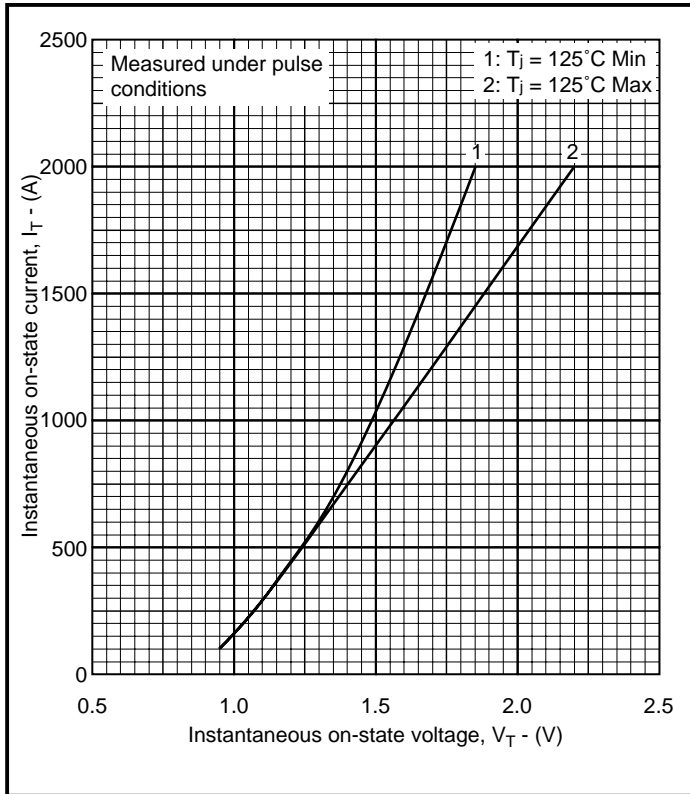


Fig. 3 Maximum (limit) on-state characteristics

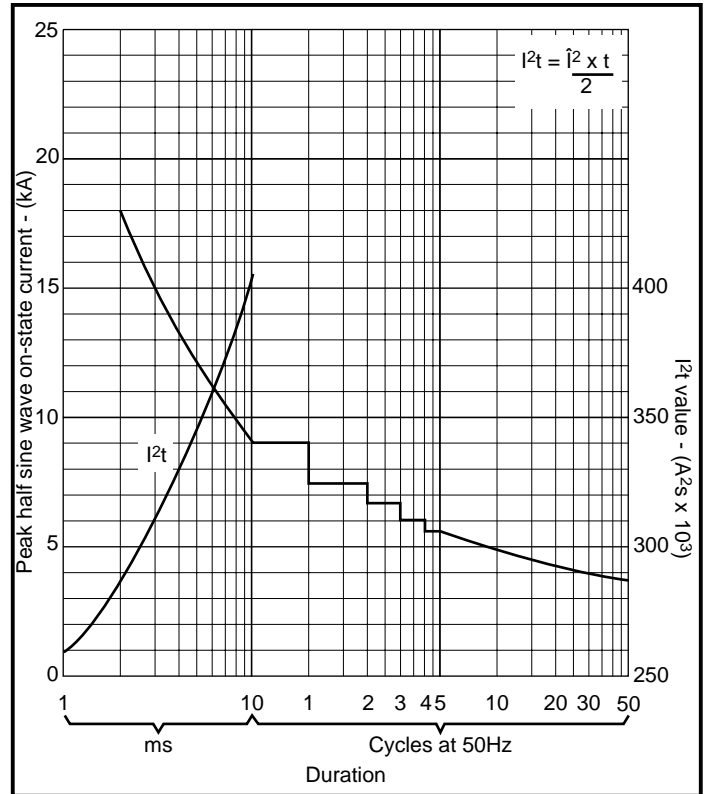


Fig. 4 Surge (non-repetitive) on-state current vs time (with 50% V_{RSM} at $T_{case} = 125^\circ\text{C}$)

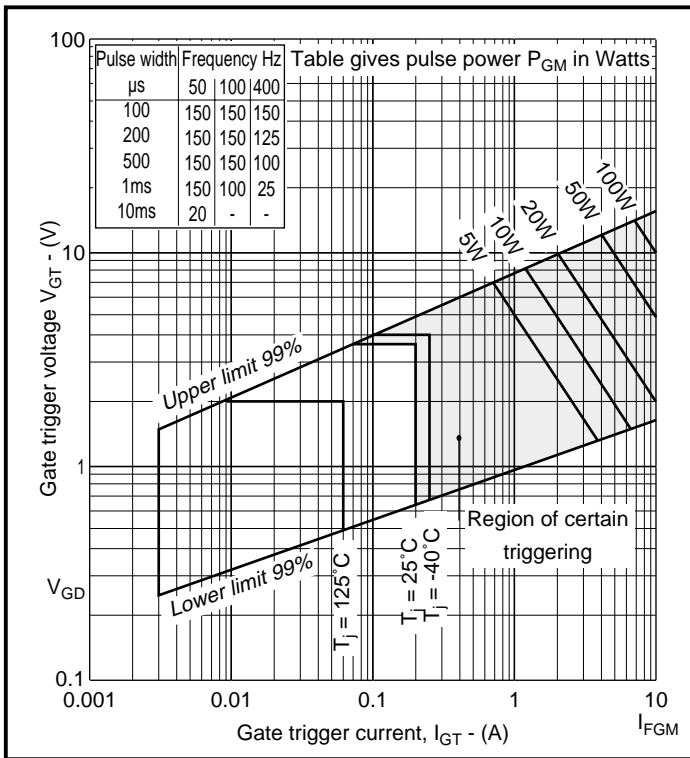


Fig. 5 Gate characteristics

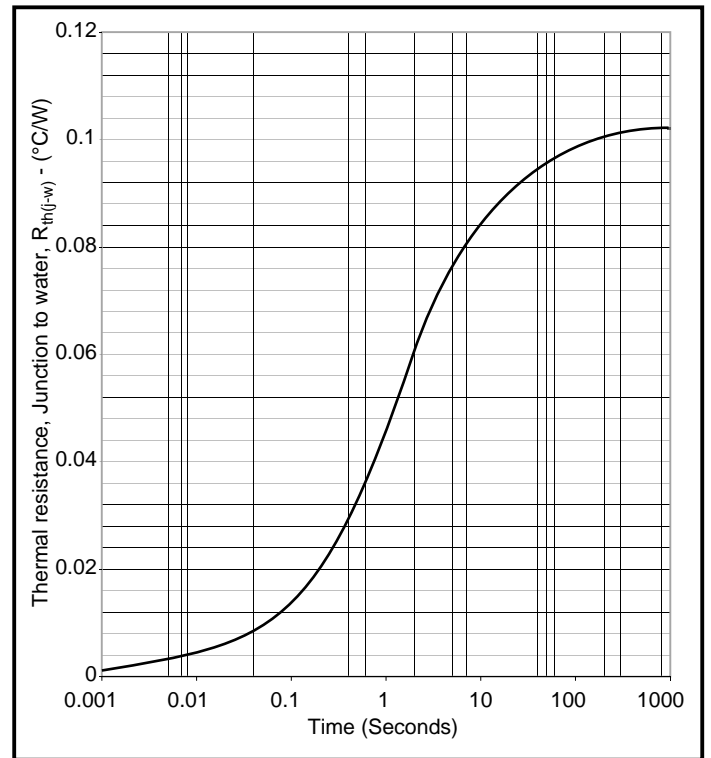
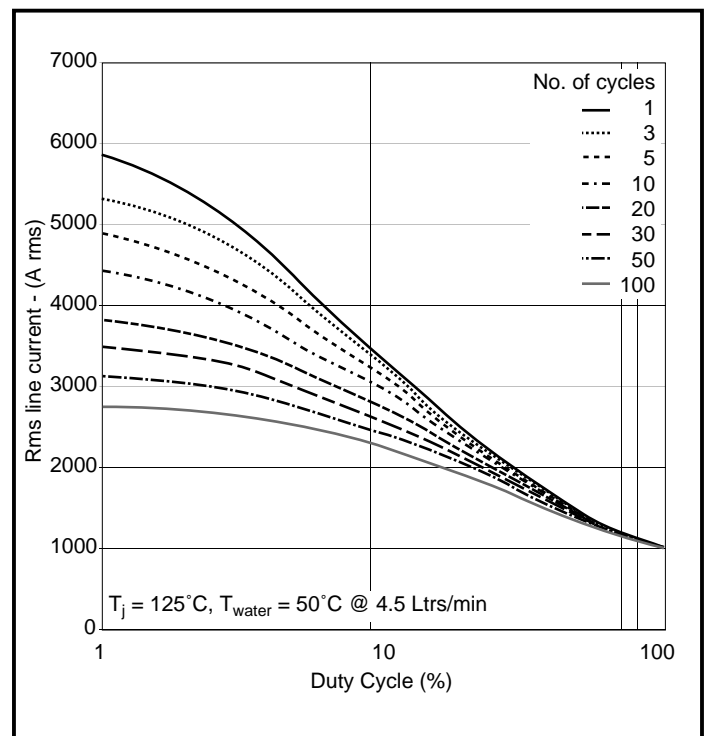
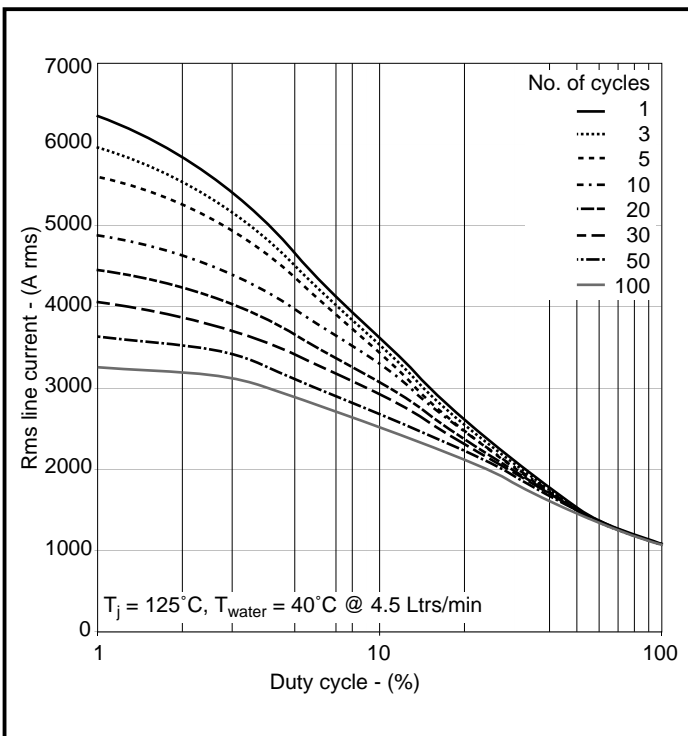
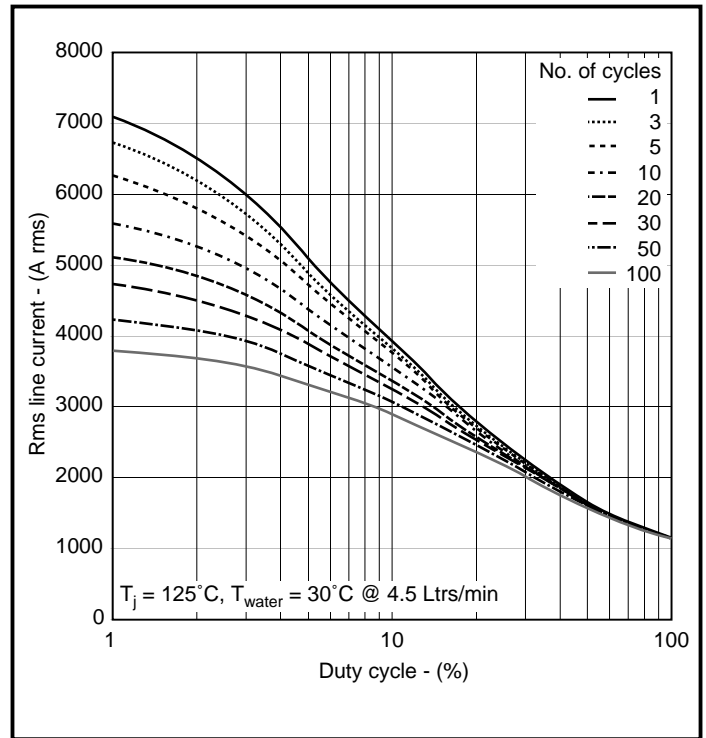
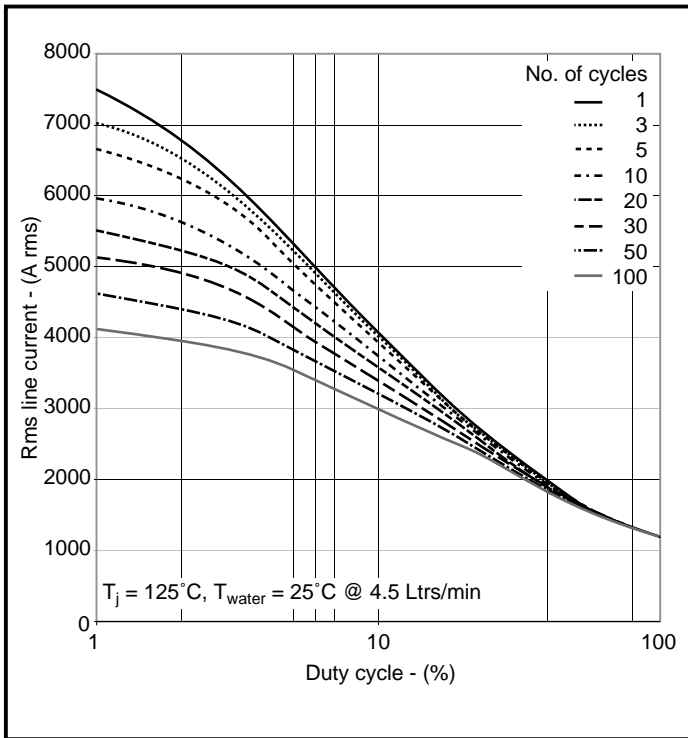


Fig. 6 Transient thermal impedance - dc



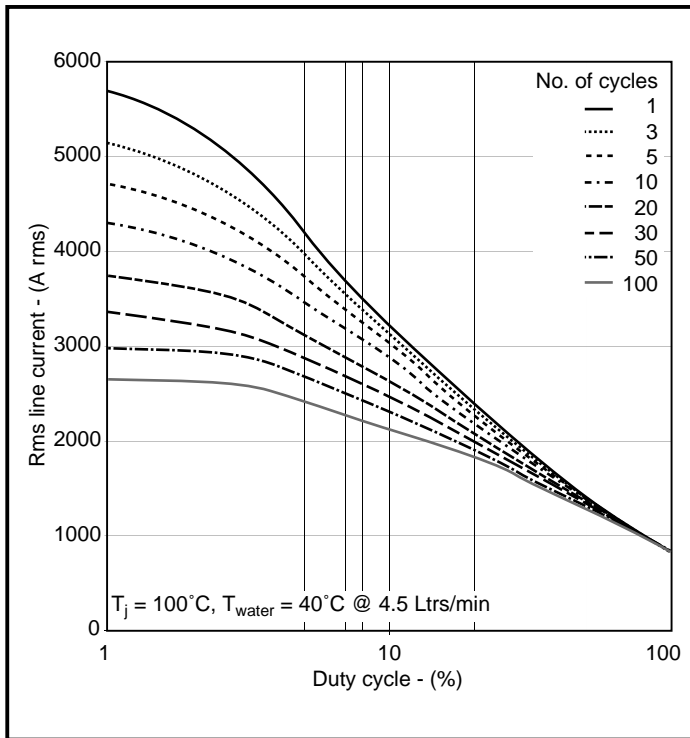
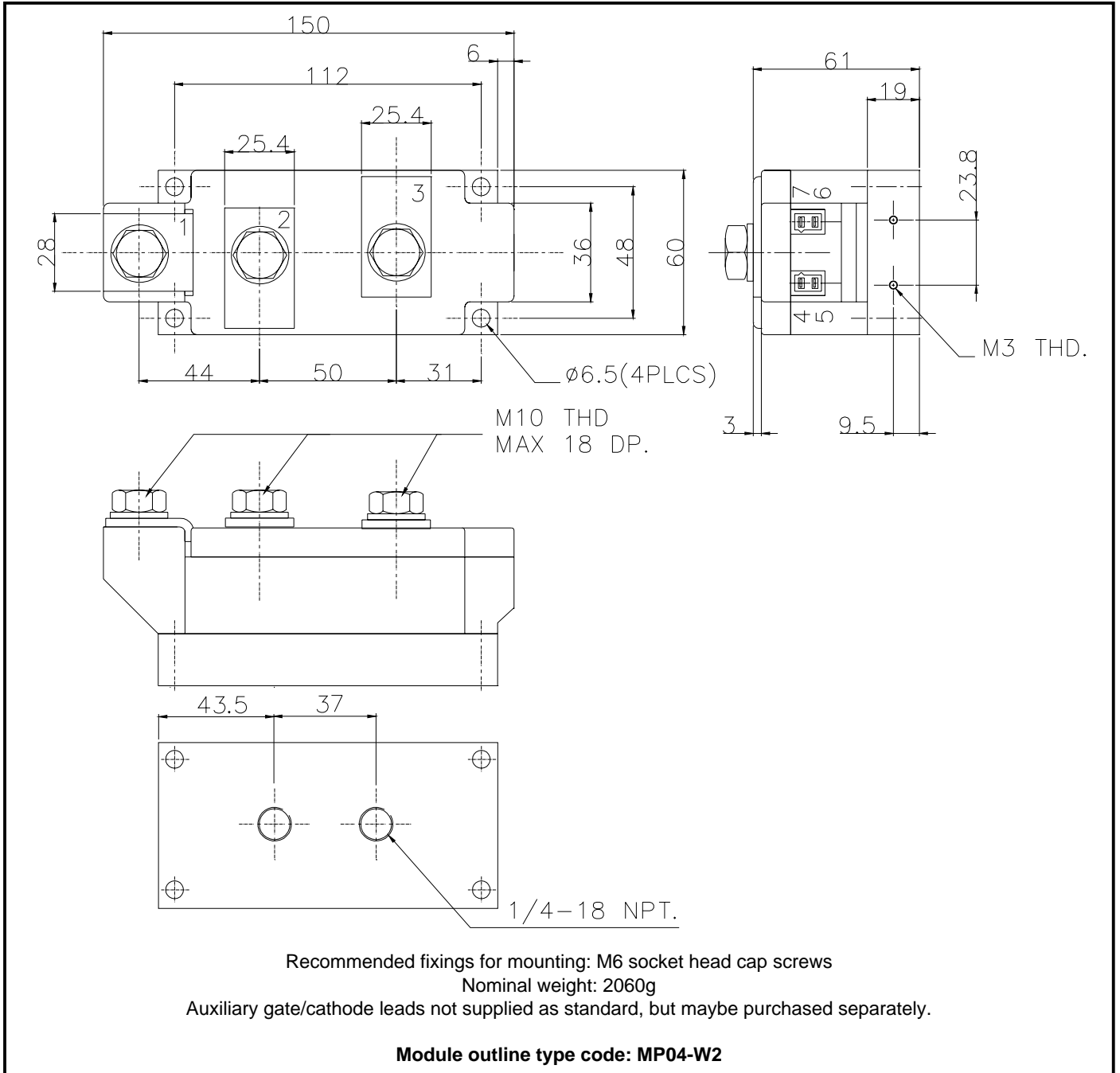


Fig. 11 Single phase welding rating @ $T_{\text{water}} = 50^\circ\text{C}$

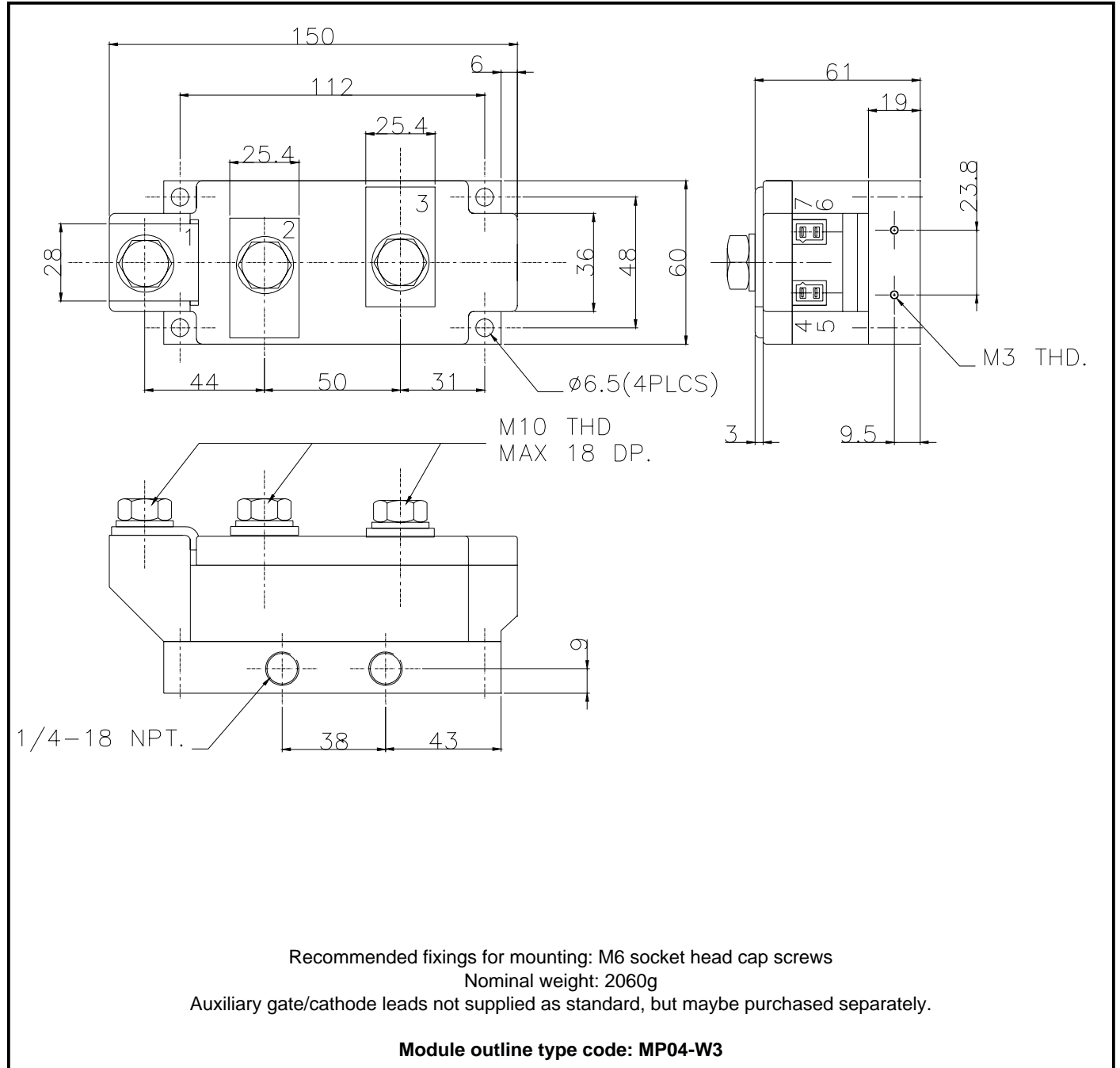
PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise.
DO NOT SCALE.



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Recommended fixings for mounting: M6 socket head cap screws

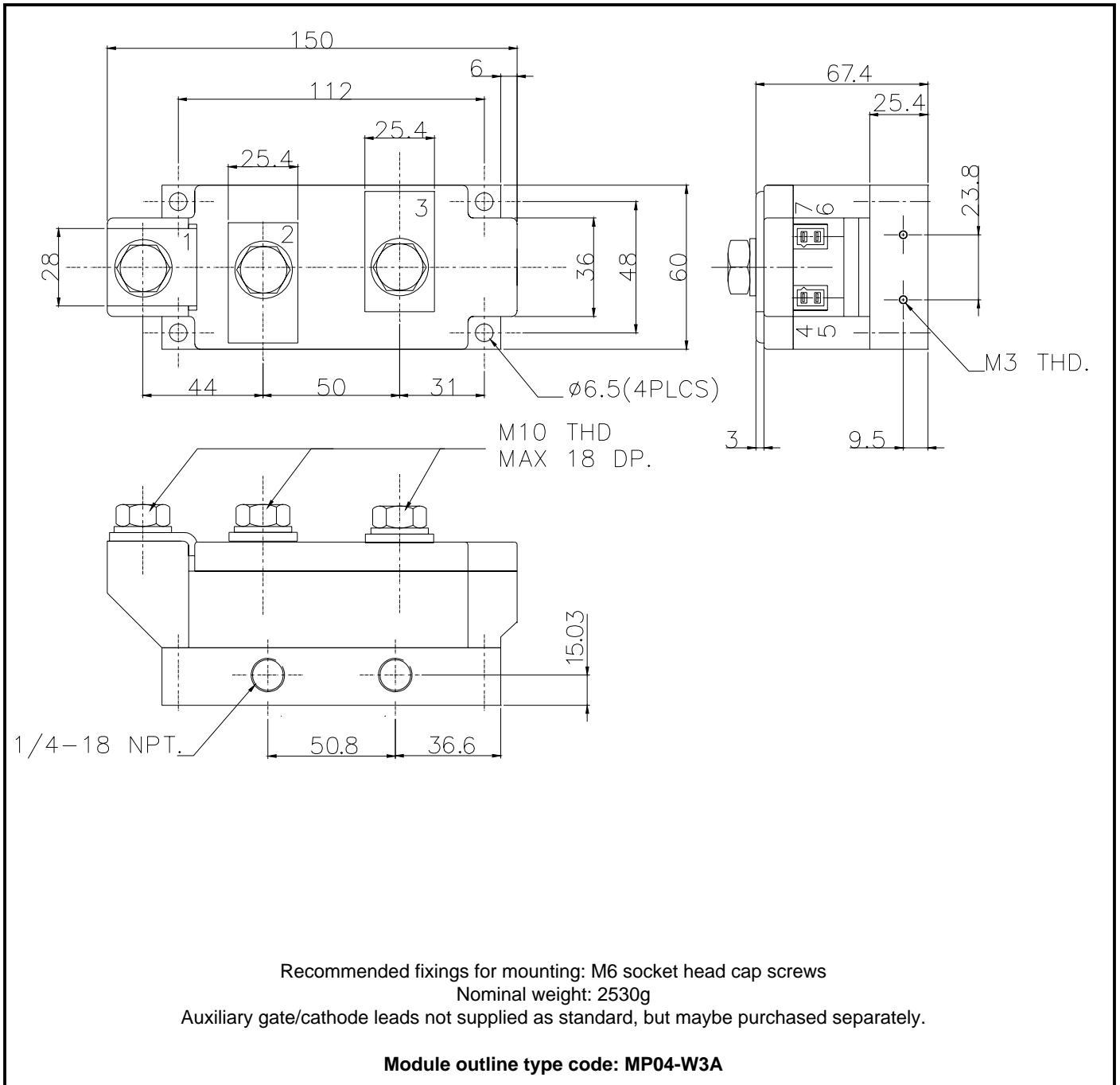
Nominal weight: 2060g

Auxiliary gate/cathode leads not supplied as standard, but maybe purchased separately.

Module outline type code: MP04-W3

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DO NOT SCALE.



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The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink and clamping systems in line with advances in device voltages and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group offers high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the latest CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete Solution (PACs).

HEATSINKS

The Power Assembly group has its own proprietary range of extruded aluminium heatsinks which have been designed to optimise the performance of Dynex semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest sales representative or Customer Services.



<http://www.dynexsemi.com>

e-mail: power_solutions@dynexsemi.com

HEADQUARTERS OPERATIONS
DYNEX SEMICONDUCTOR LTD
Doddington Road, Lincoln.
Lincolnshire. LN6 3LF. United Kingdom.
Tel: +44-(0)1522-500500
Fax: +44-(0)1522-500550

CUSTOMER SERVICE
Tel: +44 (0)1522 502753 / 502901. Fax: +44 (0)1522 500020

SALES OFFICES
Benelux, Italy & Switzerland: Tel: +33 (0)1 64 66 42 17. Fax: +33 (0)1 64 66 42 19.
France: Tel: +33 (0)2 47 55 75 52. Fax: +33 (0)2 47 55 75 59.
Germany, Northern Europe, Spain & Rest Of World: Tel: +44 (0)1522 502753 / 502901.
Fax: +44 (0)1522 500020
North America: Tel: (440) 259-2060. Fax: (440) 259-2059. Tel: (949) 733-3005. Fax: (949) 733-2986.

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